




Package	<u>EZ</u> & <u>EQ</u> 	<u>CQ</u> & <u>CQG</u> 	<u>FQ</u> 
Marki Mixer Family	<u>T3</u> (EZ & EQ) <u>M1</u> , <u>M2</u> , <u>M3</u> , <u>M4</u> (EZ only)	<u>T3</u>	<u>T3</u>
Via Type	Eyelet <sup>1</sup>	Castellation Via	Plated Through-hole
Footprint	0.600" x 0.320" (EZ) 0.400" x 0.320" (EQ)	0.400" x 0.320"	0.400" x 0.320"
Carrier Material and Thickness <sup>2</sup>	Tin/Lead(85/15) plated Brass, 0.062" <sup>4</sup>	FR4, 0.020"	PTFE, 0.010"
Hollow or Solid Bottom?	Hollow	Solid	Solid
Max Frequency of Operation	30 GHz	16 GHz	30 GHz
Suspended Substrate Compatible	Yes	No	No
ROHS (Lead-free) Compliant	No	Yes (CQG only)	No
Mounting Difficulty	Easy	Easy	Moderate
Cost	Moderate <sup>3</sup>	Low	Low
Overall Description	High performance, thick carrier eyelet technology enables the construction of suspended substrate mixer circuits in convenient SMT packages. <b>The EZ package is recommended for M1, M2, M3 and M4 mixers to 30 GHz. For T3s, CQ &amp; CQG are preferred.</b>	<b>CQ and CQG packages are recommended for all new T3 designs up to 16 GHz</b> due to their ease of mounting and low cost. <b>The CQG is the only T3 package that is ROHS compliant (i.e. lead-free).</b>	The FQ ("flatpack") package is a low cost, low profile legacy T3 package. The FQ package is <b>not recommended for new T3 designs</b> owing to its more challenging mounting procedure and lack of ROHS compliant equivalent. The CQ package is preferred.

1. The *eyelet* transition is a proprietary SMT technology designed and developed exclusively by Marki Microwave.
2. Total package height is the carrier thickness plus the lid height. Lid height is nominally 0.090". Consult package outlines for details.
3. EZ and EQ packages are slightly more expensive than CQ and FQ packages due to increased assembly cost.
4. Effective 08/10.